

(1.00 mm) .0394"

SAL1 SERIES

# HIGH-SPEED MICRO PLANE SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SAL1](http://www.samtec.com?SAL1)

**Insulator Material:**

Black LCP

**Contact Material:**

BeCu

**Plating:**

Au or Sn over

50  $\mu$ m (1.27  $\mu$ m) Ni

**Operating Temp:**

-55 °C to +125 °C

**Current Rating:**

2.9 A per pin

(2 adjacent pins powered)

**RoHS Compliant:** Yes

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max

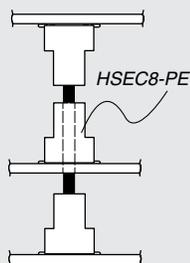
## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## OTHER SOLUTIONS



- Card pass-through option. See HSEC8-PE Series.

## ALSO AVAILABLE (MOQ Required)

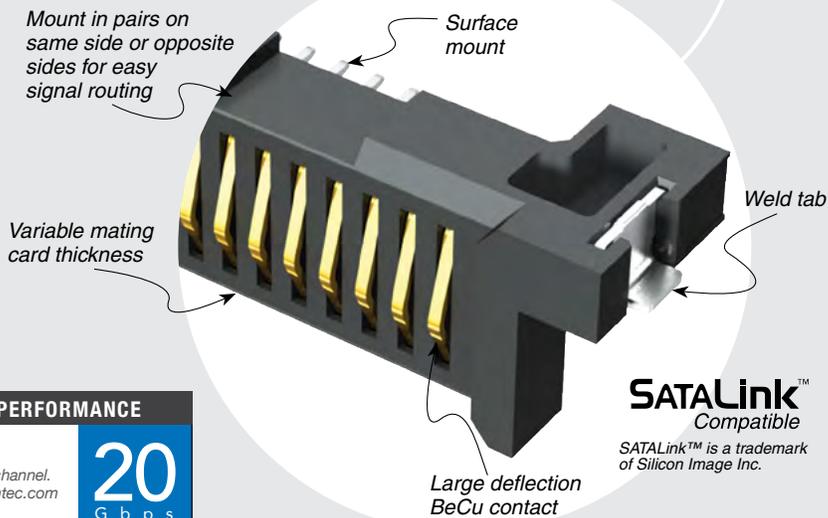
- Heavy Gold plating Contact Samtec.

### Notes:

While optimized for 50  $\Omega$  applications, this connector with alternative signal/ground patterns may also perform well in certain 75  $\Omega$  applications. Contact Samtec for further information.

Some lengths, styles and options are non-standard, non-returnable.

**Mates with:**  
(1.60 mm) .062" or  
(2.36 mm) .093" card



## HIGH-SPEED CHANNEL PERFORMANCE

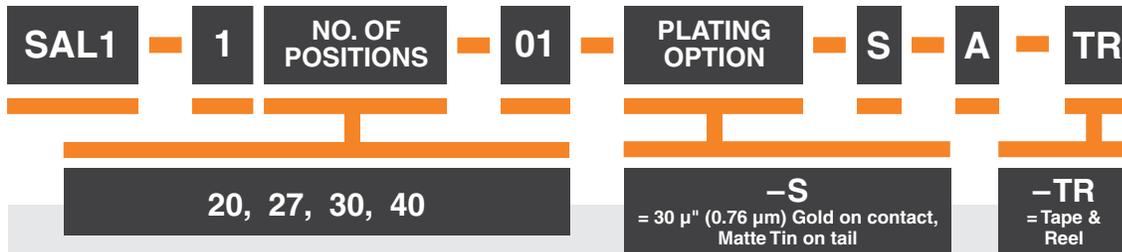
SAL1 (Top Entry)

Rating based on Samtec reference channel. For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

20  
Gbps

SATALink™  
Compatible

SATALink™ is a trademark of Silicon Image Inc.



## APPLICATIONS

